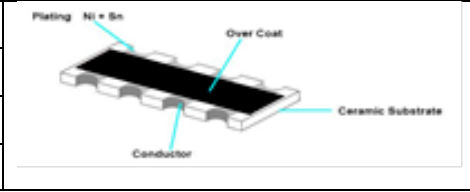


MATERIAL DECLARATION SHEET



Material Number	CAY10-J4 (LF)		
Product Line	Chip Resistor Array		
Compliance Date	2012/7/18		
RoHS Compliant	YES	MSL	1



No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CAS if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.002381686493	Aluminum dioxide	1344-28-1	96%	83.91%	87.41%
				Silicon dioxide	14808-60-7	4%	3.50%	
2	Conductor Layer	Other	0.000076837386	Silver	7440-22-4	95%	2.68%	2.82%
				Glass	65997-18-4	5%	0.14%	
3	Resistive Element	Other	0.000064031155	Ruthenium dioxide	12036-10-1	25%	0.59%	2.35%
				Silver	7440-22-4	40%	0.94%	
				Palladium	7440-05-3	15%	0.35%	
				Lead oxide	1317-36-8	20%	0.47%	
4	Over-Coating	Paint	0.000030516976	Epoxy	25068-38-6	100%	1.12%	1.12%
5	Marking	Ink	0.000003269676	Epoxy	25068-38-6	100%	0.12%	0.12%
6	End Terminal	Metal	0.000002452257	Nickel	7440-02-0	80%	0.07%	0.09%
				Chromium	7440-47-3	20%	0.02%	
7	Ni Plating	Metal	0.000087736306	Nickel	7440-02-0	100%	3.22%	3.22%
8	Tin Plating	Metal	0.000078199751	Tin	7440-31-5	100%	2.87%	2.87%
Total weight			0.00272473					

This Document was updated on: **2012/7/23**

Important remarks: Resistive Element contains the Lead (Pb) which can be referred to RoHS Exemption 7(c)-I